



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

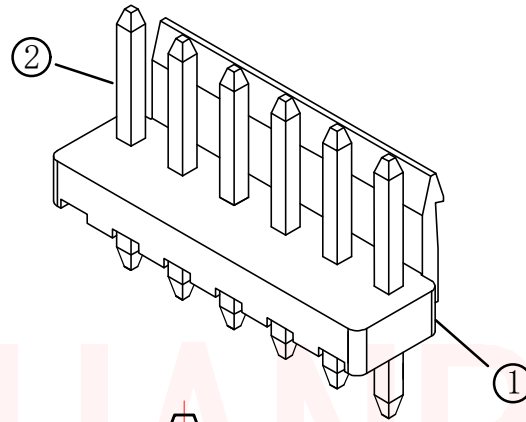
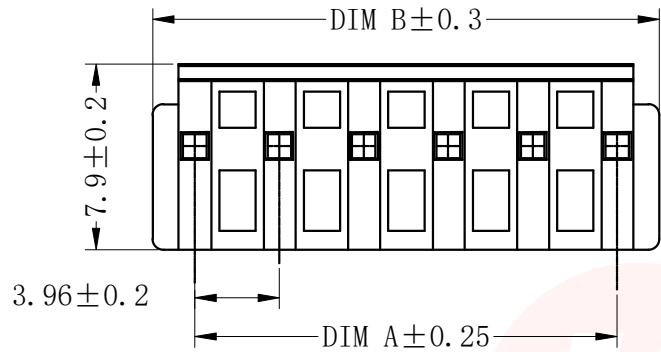
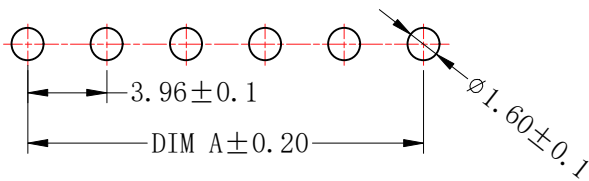
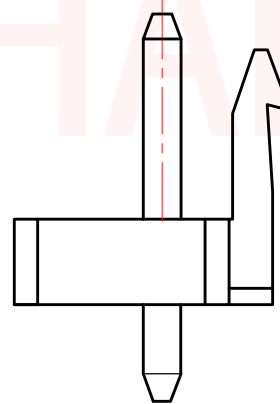
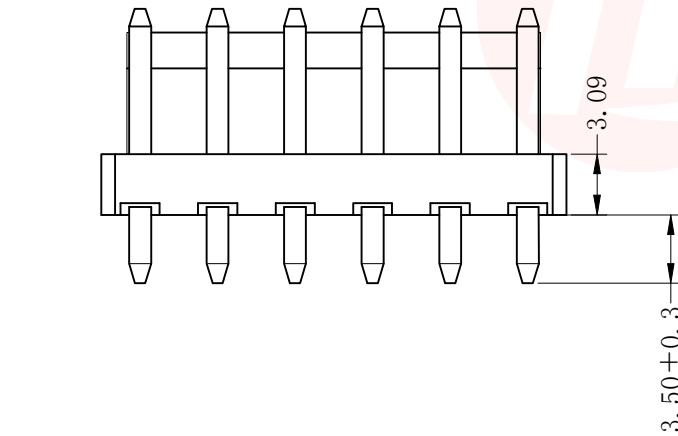


TABLE:

CSG PART NO.	Dimension mm		
	PIN	A	B
WAFER-VH396Z-2A	2P	3.96	7.92
WAFER-VH396Z-3A	3P	7.92	11.88
WAFER-VH396Z-4A	4P	11.88	15.84
WAFER-VH396Z-5A	5P	15.84	19.80
WAFER-VH396Z-6A	6P	19.80	23.76
WAFER-VH396Z-7A	7P	23.76	27.72
WAFER-VH396Z-8A	8P	27.72	31.68
WAFER-VH396Z-9A	9P	31.68	35.64
WAFER-VH396Z-10A	10P	35.64	39.60
WAFER-VH396Z-11A	11P	39.60	43.56
WAFER-VH396Z-12A	12P	43.56	47.52
WAFER-VH396Z-13A	13P	47.52	51.48
WAFER-VH396Z-20A	20P	75.24	79.20



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

- 1、塑件材料: PA66 (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻: $\leq 20m\Omega$
- 4、绝缘电阻: $\geq 1000M\Omega$
- 5、额定电压: 250V AC DC
- 6、额定电流: 3.0A AC DC
- 7、耐压: 能承受1000V AC/Minute
- 8、工作温度: $-25^{\circ} \sim +105^{\circ}$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 235^{+5}_{-0} , 时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

序号	名称	材料	电镀 (锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	
2	基座/Wafer	PA66 (UL94V-0)	白色
UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS: ANGLES:		TITLE: WAFER VH 3.96MM 直针 DIP TYPE	
X	:±0.20	X	:±2°
X.X	:±0.10	X.X	:±1°
X.XX	:±0.05		
DWN	xiong	PART NO. WAFER-VH396Z-NA	
CHKD	lee	SCALE: 1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET: 10F 1
REV: A4			
CUSTOMER COPY			